

Filename: PMP8549RevA - BoM.xls

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## PMP8549RevA - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
4	C1, C4, C12, C102	100nF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
1	C10	220nF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
5	C2, C3, C7, C8, C101	22uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	Std	Std
1	C5	220uF	Capacitor, Aluminum Electrolytic, 25V, 20%	0.328 x 0.390 inch	EEEFK1E221P	Panasonic
1	C9	10nF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
1	D2	MBRA140	Diode, Schottky, 1A, 40V	SMA	MBRA140T3G	ON Semi
1	J1	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	0.41 x 0.25 inch	ED555/3DS	OST
1	JP1	PTC36SAAN	Header, 2-pin, 100mil spacing, (36-pin strip)	0.100 inch x 2	PTC36SAAN	Sullins
1	L1	68uH	Inductor, SMT, 185mOhm, 1.5A rms, 1.5A sat	0.402 x 0.394 inch	744066680	Wuerth
1	L101	2.2uH	Inductor, SMT, 34mOhm, 2.5A rms, 3.4A sat	4.0 x 4.5 mm	744773022	Wuerth
1	R1	2.55k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	10.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R11	1.40k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R2	69.8k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	402k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	11.5k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	49.9	Resistor, Chip, 1/16W, 1%	603	Std	Std
6	TP1, TP2, TP3, TP4, TP13, TP14	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
3	TP10, TP12, TP16	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
1	U1	TPS54260	IC, DC-DC Converter With Eco-Mode, 2.5A, 60V	MSOP-10	TPS54260DGQ	Texas Instruments

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